



MJ N-Channel Super Trench Power MOSFET

Description

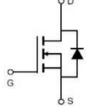
The MJXP1550JG uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

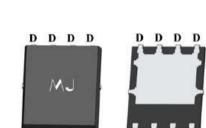
Application

DC/DC Converter

General Features

- VDS=145V,ID=50A
 RDS(ON) <19mΩ @ VGS=10V
- Excellent gate charge x RDS(on) product(FOM)
- Very low on-resistance RDS(on)
- ◆ 150°C operating temperature
- Pb-free lead plating
- ♦ 100% UIS tested





GSSS

Ideal for high-frequency switching and synchronous rectification

Schematic Diagram

Top View Bottom View

G

SSS

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJXP1550JG	MJXP1550JG	DFN5X6-8L	1	2	<u>.</u>

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	145	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lD	50	А
Drain Current-Continuous(Tc =100°C)	ID(100℃)	35.4	А
Pulsed Drain Current	Ідм	200	А
Maximum Power Dissipation	PD	125	W
Derating factor		1	W/°C
Single pulse avalanche energy (Note 5)	Eas	210	mJ
Operating Junction and Storage Temperature Range	ТЈ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	1	°C/W	
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Electrical Characteristics (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics		1	1		1	1
Drain-Source Breakdown Voltage	BVdss	V _{GS} =0V I₀=250µA	145	-	-	V
Zero Gate Voltage Drain Current	loss	VDS=145V,VGS=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	VDS=±20V,VDS=0V	-	-	±100	nA
On Characteristics (Note 3)		1	1	1	1	1
Gate Threshold Voltage	VGS(th)	Vos=Vos,Io=250µA	2.5	-	4.5	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V,I _D =30A	-	15	19	mΩ
Forward Transconductance	G FS	VDS=10V,ID=30A	-	40	-	s
Dynamic Characteristics (Note 4)			1	1	1	1
Input Capacitance	Clss		-	5000	-	PF
Output Capacitance	Coss	VDS=75V,VGS=0V F=1.0MHz	-	192	-	PF
Reverse Transfer Capacitance	Crss		-	9.5	-	PF
Switching Characteristics (Note 4)		1		1	1	1
Turn-on Delay Time	td(on)		-	21	-	nS
Turn-on Rise Time	tr	Vdd=75V,Id=30A	-	20	-	nS
Turn-Off Delay Time	td(off)	Vgs=10V,Rg=4.7Ω	-	40	-	nS
Turn-Off Fall Time	tr		-	10	-	nS
Total Gate Charge	Qg		-	59.8	-	nC
Gate-Source Charge	Qgs	Vds=75V,Id=30A Vgs=10V	-	28.2	-	nC
Gate-Drain Charge	Qgd		-	7.1	-	nC
Drain-Source Diode Characteristics		1	<u> </u>	1	1	<u> </u>
Diode Forward Voltage (Note 3)	Vsd	V _{GS} =0V,I _S =30A	-	-	1.2	V
Diode Forward Current (Note 2)	ls		-	-	50	A
Reverse Recovery Time	trr	TJ=25°C, IF=Is	-	58	-	nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs ^(Note 3)	-	135		nC

Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Surface Mounted on FR4 Board, t ≤ 10 sec.

(3) Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

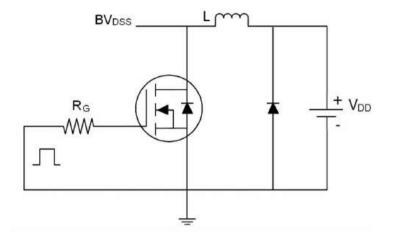
(4) Guaranteed by design, not subject to production

(5) EAS condition: Tj=25°C, VDD=50V, VG=10V, L=0.5mH, Rg=25\Omega

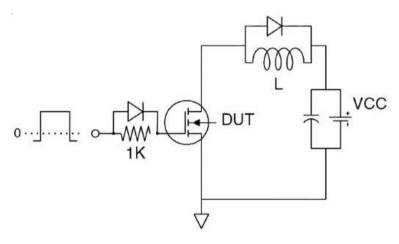




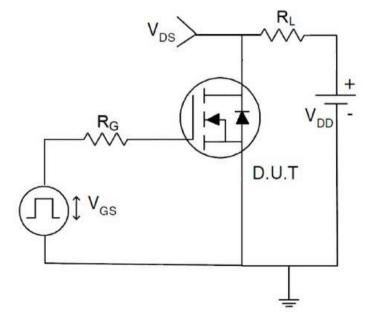
Test circuit







Gate charge test Circuit



Switch Time Test Circuit





Typical Electrical and Thermal Characteristics

RoHS

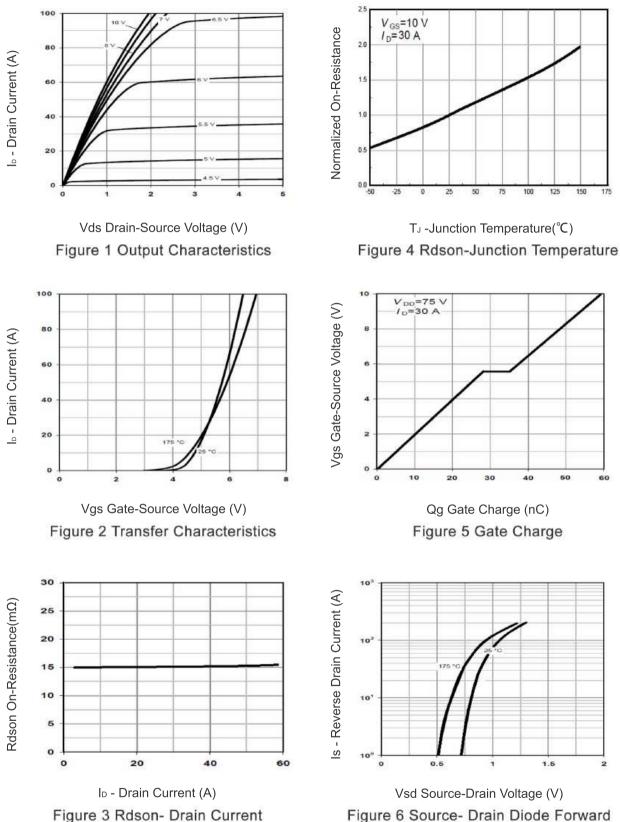


Figure 6 Source- Drain Diode Forward





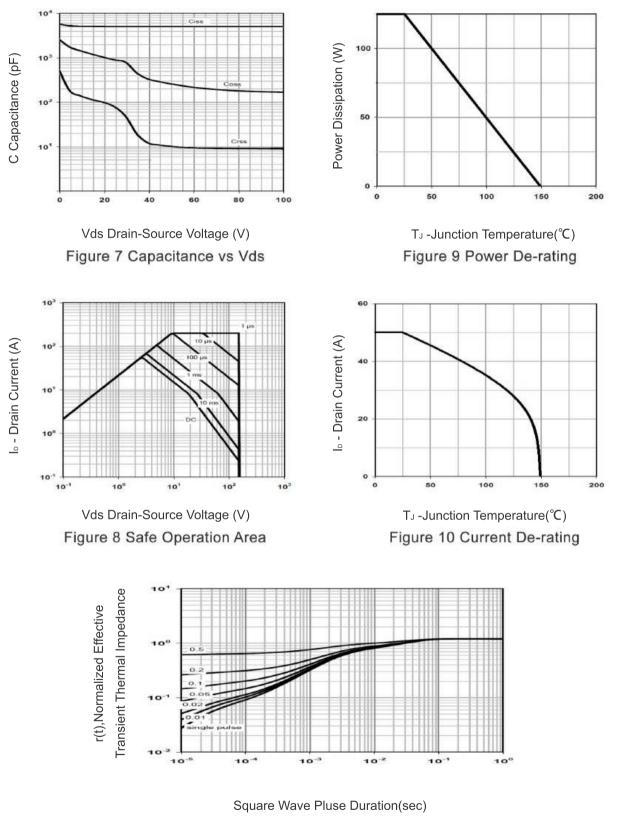
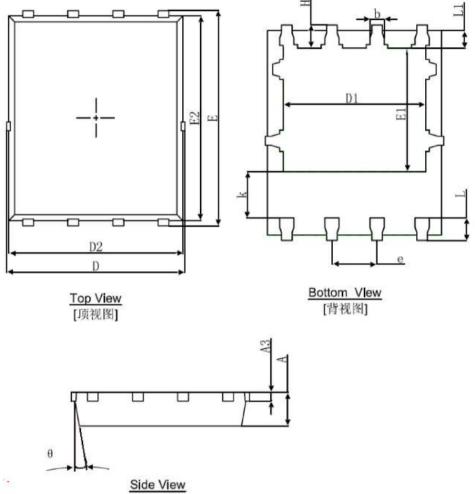


Figure 11 Normalized Maximum Transient Thermal Impedance







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Complex	Dimensions	In Millimeters	Dimension	ns in Inches
Symbol	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254	4REF.	0.010	DREF.
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270	OTYP.	0.050	DTYP.
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
н	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°





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